

EP5031 FLEXIBLE EPOXY POTTING – ENCAPSULATING COMPUND

• PRODUCT DESCRIPTION

EP5031 is an unfilled very flexible elastomeric type epoxy potting compound with low viscosity and high clarity. Excellent solution for stress free components with its thermal shock properties. Suitable for rework in electrical and electronic components.

• CURING PROPERTIES

25°C	65°C	100°C
24 hours	2-3 hours	1-2 hours
Pot Life: 50 min @ 25° C		

• PHYSICAL PROPERTIES

Color	Clear
Viscosity	1000 cps (mixed)
Specific Gravity	1,03
Mix Ratio	100:70 (by weight)
	100:80 (by volume)

• CURED PROPERTIES

Temperature Resistance (°C)	-65 to +130
Hardness Shore A	80
Tensile Strength (MPA)	19
Compressive Strength (MPA)	35
Thermal Conductivity (W/mK)	0,2
Moisture Absorption	
• 10 Days @ 25°C	% 0.30
Thermal Stability	
• 1000 Hrs. @ 125°C, Wt. Loss	% 0.62



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Volume Resistivity <ul style="list-style-type: none">@ 25° C, ohm-cm	6x10 ¹³
Dielectric Strength (volts/mil)	425
Dielectric Constant <ul style="list-style-type: none">@ 25° C, 100 KC	4.0
Dissipation Factor <ul style="list-style-type: none">@ 25° C, 100 KC	0.021

● INSTRUCTIONS FOR USE

The surfaces should be free of dust, oil and other dirt in order to obtain an optimal efficient bond.

Shelf life: Store in original, unopened containers for 12 months at room temperature.

The resin of part B might cristalize during storage. This process is reversible by heating (1 hour @ 40°C).

